



3.2.3 Beam Lead Chips (Method 2, Figure 2)

- 3.2.3.1 The chips shall be arranged and oriented on the glass retainer in accordance with Paragraphs 3.2.2.1 and 3.2.2.2.
- 3.2.3.2 A second glass retainer, per Paragraph 3.2.2.1, shall be positioned on top of the chips and shall be secured to the first glass retainer at each of the four corners with two layers of double-faced tape (minimum thickness to prevent contact of top glass with chips), each having a maximum size of 3/8 inch square or diameter.
- 3.2.3.3 The bottom glass retainer shall be marked with the chip part and lot number.
- 3.2.3.4 The assembly shall be inserted into a clear, rigid plastic box with hinged cover and Snap-Lok closure (Figure 1). The second glass retainer shall be on top in the box.
- 3.2.3.5 Four pads of soft-density foam cushion shall be arranged in the box, two in the body in two



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**Commodity**

Clip, Tray

Cushioning, Cellulosic

Cushioning, Polyurethane

Double-Back Tape

Film, Static Protective

Sheet, Plastic

**Military/Commercial Specifications**

Fluoroware Inc., Chaska, MN

PPP-C-843

MIL-P-26514, Type I MIL-P-26514, Type I

Avery Products "Fasson" or equal, Santa Ana, CA

QPL MIL-B-81705

L-P-376, Type I, Flexible



